

### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

	BVDSS	RDS(ON)	ID
Q1	30V	9.5mΩ	43A
Q2	30V	4.2mΩ	85A

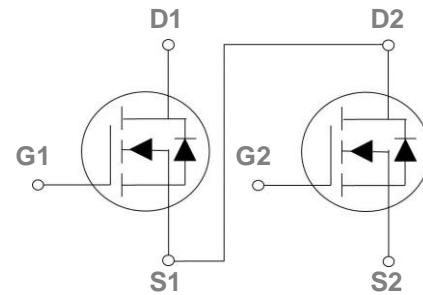
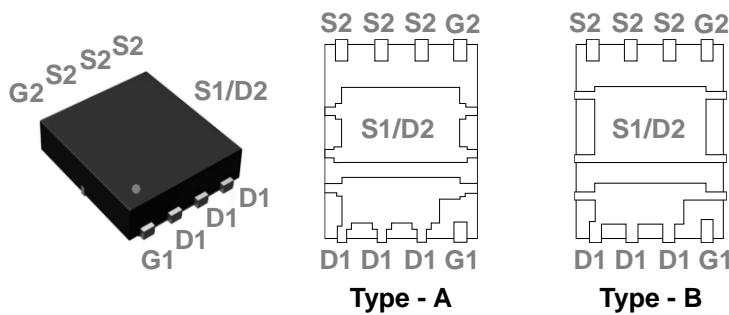
### Features

- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- MB / VGA / Vcore
- POL Buck Applications
- SMPS 2<sup>nd</sup> SR

### PPAK5x6 Asymmetric Dual Pin Configuration



### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Q1	Q2	Units
$V_{DS}$	Drain-Source Voltage	30	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	43	85	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	27.2	54	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup> , Chip/Package Limit	172	340	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	45	88	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	30	42	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	27.2	48	W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.22	0.38	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150		$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150		$^\circ\text{C}$



30V N-Channel MOSFETs

PDC3803R

## Thermal Characteristics

Symbol		Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Q1	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJA</sub>	Q2		---	62	°C/W
R <sub>θJC</sub>	Q1	Thermal Resistance Junction to Case	---	4.6	°C/W
R <sub>θJC</sub>	Q2		---	2.6	°C/W

## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

### Static State Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250μA	Q1	30	---	---
			Q2	30	---	---
△BV <sub>DSS</sub> /△T <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	Q1	---	0.04	---
			Q2	---	0.03	---
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	Q1	---	---	1
			Q2	---	---	1
		V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =125°C	Q1	---	---	10
			Q2	---	---	10
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	Q1	---	---	±100
			Q2	---	---	±100
R <sub>DSON</sub>	Static Drain-Source On-Resistance <sup>3</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =8A	Q1	---	7.5	9.5
		V <sub>GS</sub> =10V , I <sub>D</sub> =20A	Q2	---	3.3	4.2
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =5A	Q1	---	11	14.5
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A	Q2	---	4.5	6
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	Q1	1	1.6	2.5
			Q2	1	1.6	2.5
△V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	Q1	---	-4	---
			Q2	---	-5	---
gfs	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =8A	Q1	---	9.5	---
		V <sub>DS</sub> =10V , I <sub>D</sub> =10A	Q2	---	15.5	---

### Dynamic Characteristics

$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{DS}=15V$ , $V_{GS}=4.5V$ , $I_D=10A$	Q1	---	7.5	12	nC
$Q_{gs}$	Gate-Source Charge <sup>3, 4</sup>		Q2	---	24	34	
$Q_{gd}$	Gate-Drain Charge <sup>3, 4</sup>		Q1	---	1.3	2.6	
			Q2	---	4.2	6	
			Q1	---	4.5	8	
			Q2	---	13	18	
$T_{d(on)}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{DD}=15V$ , $V_{GS}=10V$ , $R_G=3.3\Omega$ $I_D=8A$	Q1	---	4.8	9	ns
$T_r$	Rise Time <sup>3, 4</sup>		Q2	---	12.6	24	
$T_{d(off)}$	Turn-Off Delay Time <sup>3, 4</sup>		Q1	---	12.5	24	
$T_f$	Fall Time <sup>3, 4</sup>		Q2	---	19.5	37	
			Q1	---	27.6	52	
			Q2	---	42.8	81	
			Q1	---	8.2	16	
			Q2	---	13.2	25	

$C_{iss}$	Input Capacitance	$V_{DS}=25V$ , $V_{GS}=0V$ , $F=1MHz$	Q1	---	680	1000	pF
$C_{oss}$	Output Capacitance		Q2	---	2200	3190	
$C_{rss}$	Reverse Transfer Capacitance		Q1	---	150	220	
$C_{rss}$	Reverse Transfer Capacitance		Q2	---	280	405	
$R_g$	Gate resistance		Q1	---	70	105	
$R_g$	Gate resistance		Q2	---	177	255	
		$V_{GS}=0V$ , $V_{DS}=0V$ , $F=1MHz$	Q1	---	2.7	5.4	$\Omega$
			Q2	---	2	4	$\Omega$

### Guaranteed Avalanche Energy

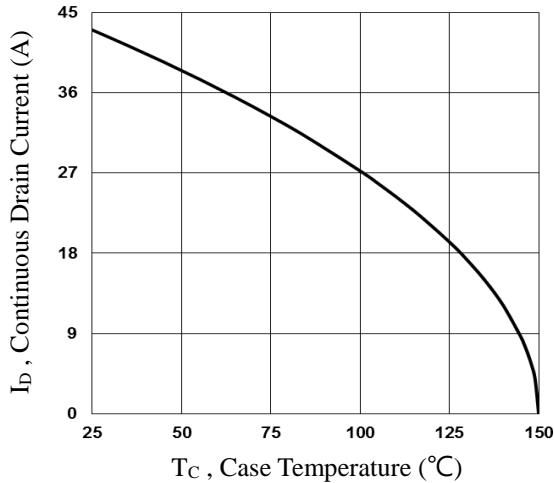
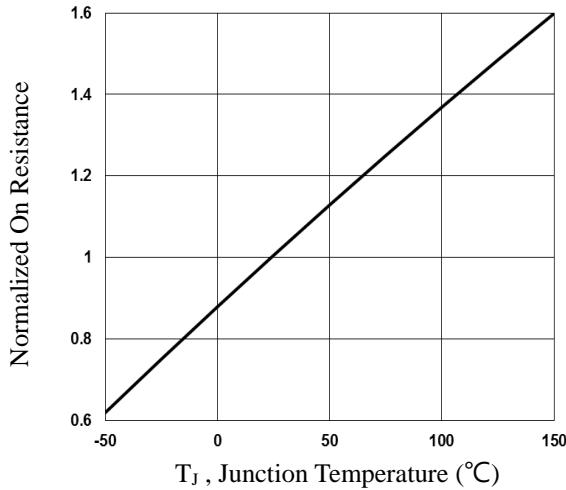
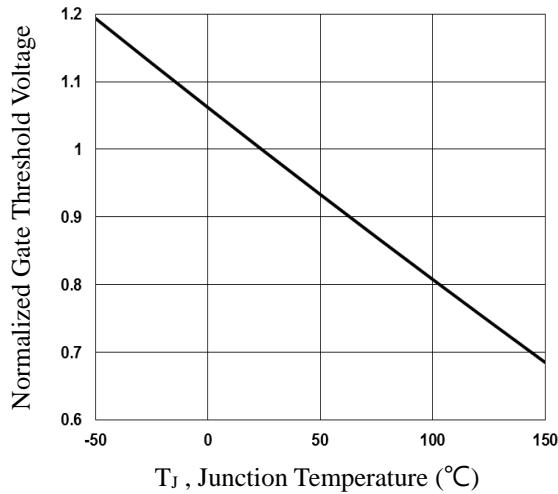
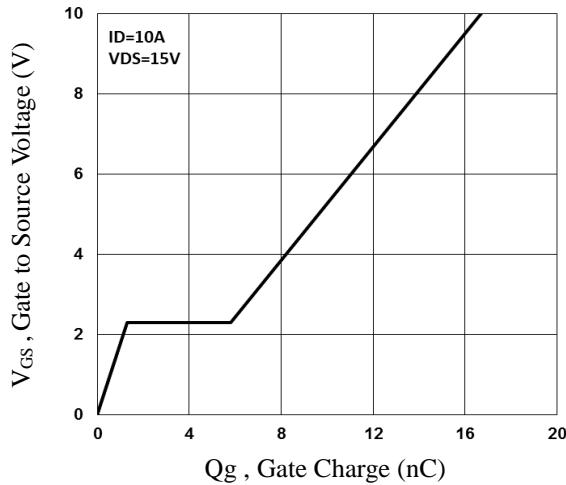
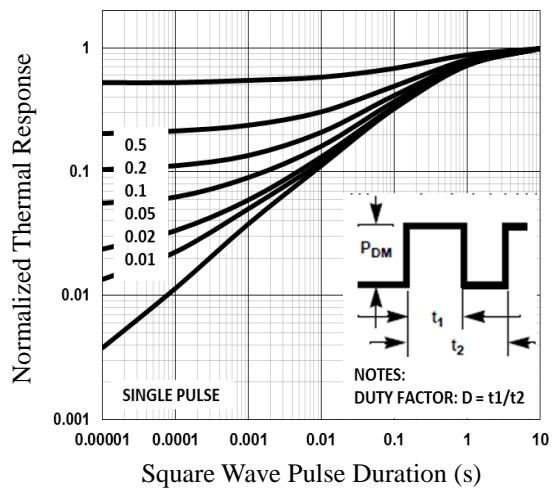
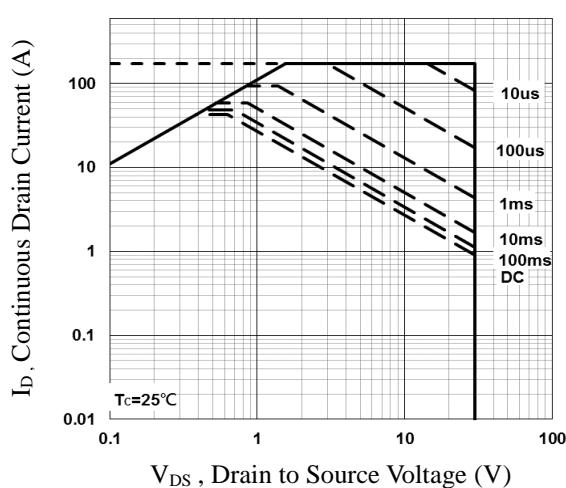
Symbol	Parameter	Conditions		Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	$V_{DD}=25V$ , $L=0.1mH$ , $I_{AS}=21A$	Q1	22	---	---	mJ
		$V_{DD}=25V$ , $L=0.1mH$ , $I_{AS}=29A$	Q2	42	---	---	mJ

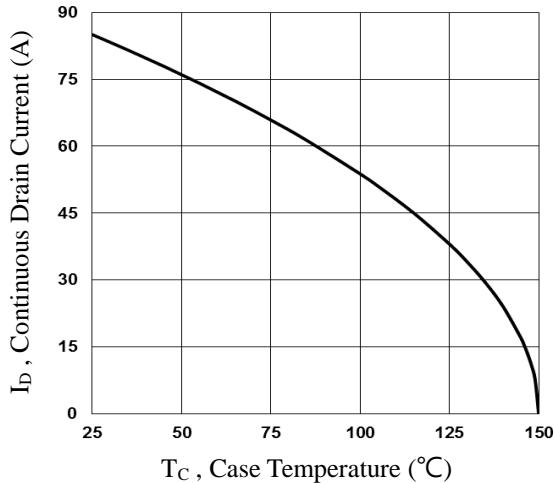
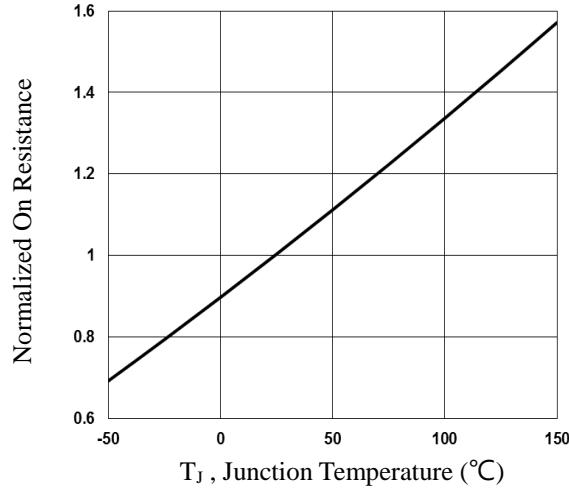
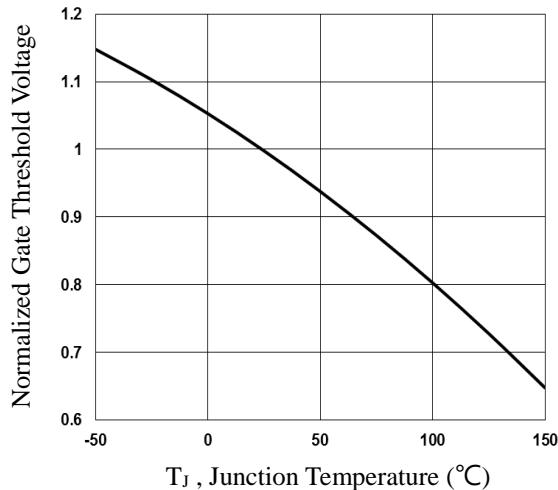
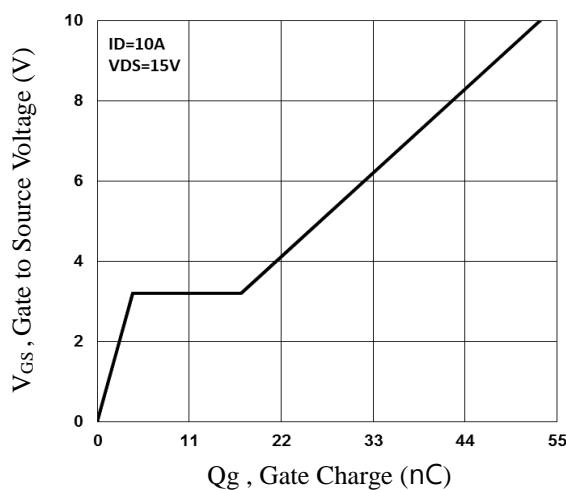
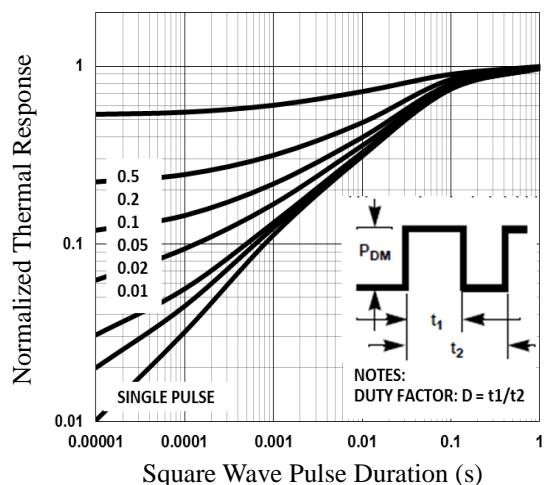
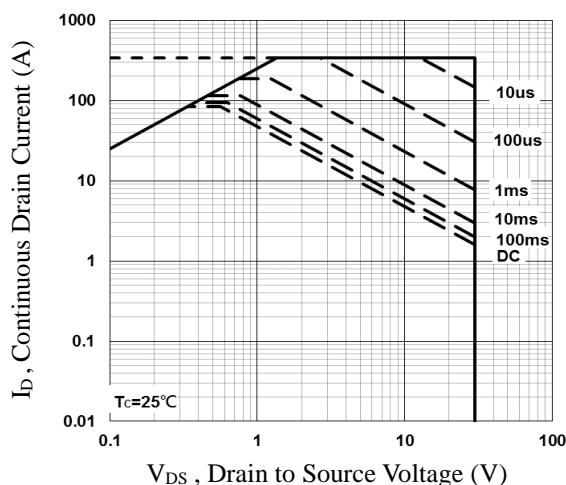
### Drain-Source Diode Characteristics

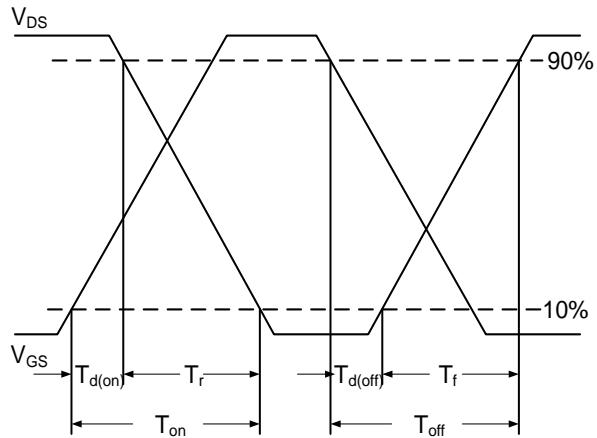
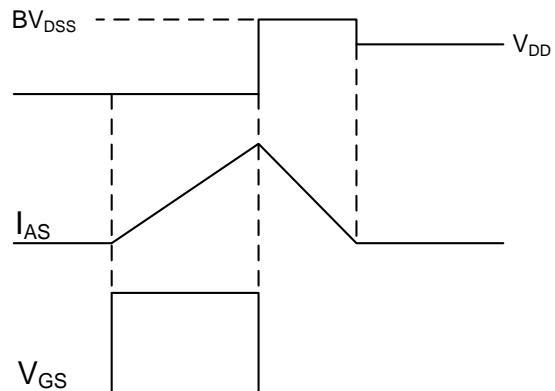
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
Is	Continuous Source Current	$V_G=V_D=0V$ , Force Current	Q1	---	---	43	
			Q2	---	---	85	
IsM	Pulsed Source Current <sup>3</sup>		Q1	---	86	A	
			Q2	---	170	A	
VSD	Diode Forward Voltage <sup>3</sup>	$V_{GS}=0V$ , $I_S=1A$ , $T_J=25^\circ C$	Q1	---	1	V	
			Q2	---	1	V	

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V$ ,  $V_{GS}=10V$ ,  $L=0.1mH$ , Q1: $I_{AS}=30A$ , Q2: $I_{AS}=42A$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ C$ .
3. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

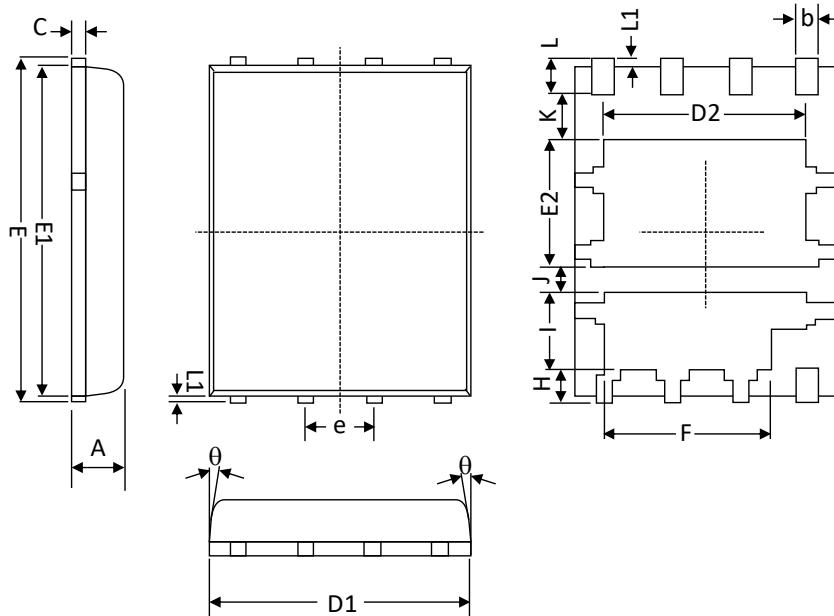

**Fig.1 Q1 Continuous Drain Current vs.  $T_c$** 

**Fig.2 Q1 Normalized  $R_{DS(on)}$  vs.  $T_j$** 

**Fig.3 Q1 Normalized  $V_{th}$  vs.  $T_j$** 

**Fig.4 Q1 Gate Charge Waveform**

**Fig.5 Q1 Normalized Transient Impedance**

**Fig.6 Q1 Maximum Safe Operation Area**


**Fig.7 Q2 Continuous Drain Current vs. T<sub>c</sub>**

**Fig.8 Q2 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>**

**Fig.9 Q2 Normalized V<sub>th</sub> vs. T<sub>J</sub>**

**Fig.10 Q2 Gate Charge Waveform**

**Fig.11 Q2 Normalized Transient Impedance**

**Fig.12 Q2 Maximum Safe Operation Area**

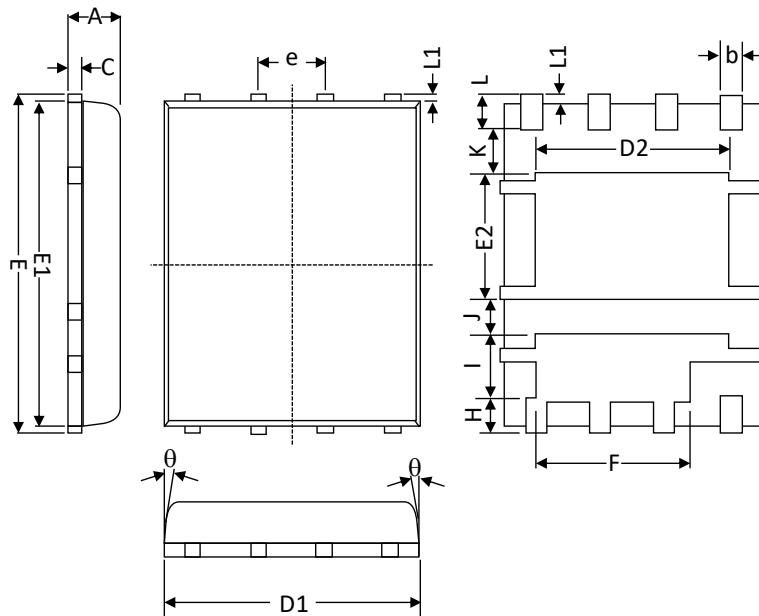

**Fig.13 Switching Time Waveform**

**Fig.14 EAS Waveform**

## PPAK5x6 Asymmetric Dual Package Information

Type - A



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.850	1.100	0.033	0.043
b	0.250	0.510	0.010	0.020
C	0.150	0.300	0.006	0.012
D1	4.800	5.300	0.189	0.209
D2	3.600	3.960	0.142	0.156
E	5.900	6.200	0.232	0.244
E1	5.400	5.850	0.213	0.230
E2	2.000	2.450	0.079	0.096
e	1.270 BSC		0.050 BSC	
F	2.550	3.250	0.100	0.128
H	0.430	0.810	0.017	0.032
I	1.100	1.420	0.043	0.056
J	0.300	0.600	0.012	0.024
K	0.500	-	0.020	-
L	0.350	0.800	0.014	0.031
L1	0.060	0.350	0.002	0.014
θ	0°	14°	0°	14°

**Type - B**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.000	0.035	0.039
b	0.250	0.510	0.010	0.020
C	0.200	0.300	0.008	0.012
D1	5.100	5.300	0.201	0.209
D2	3.610	3.960	0.142	0.156
E	5.950	6.150	0.234	0.242
E1	5.400	5.700	0.213	0.224
E2	2.050	2.300	0.081	0.091
e	1.270 BSC		0.050 BSC	
F	2.870	3.220	0.113	0.127
H	0.480	0.680	0.019	0.027
I	1.200	1.400	0.047	0.055
J	0.400	0.600	0.016	0.024
K	0.500	-	0.020	-
L	0.600	0.800	0.024	0.031
L1	0.150	0.350	0.006	0.014
θ	0°	14°	0°	14°